

MULTILAYER CERAMIC CHIP CAPACITORS



C Series Low ESL Flip Type

Type: C0510 [EIA CC0204]

C0816 [EIA CC0306] C1220 [EIA CC0508] C1632 [EIA CC0612]

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TDK MLCC US Catalog

Version B11

REMINDERS

Please read before using this product

SAFETY REMINDERS



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C Series Low ESL Flip Type Type: C0510, C0816, C1220, C1632

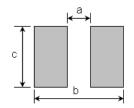
Features



- · Positioning the electrodes along the length of the chip device, reduces ESR and ESL components over conventional products.
- · Provides high frequency noise suppression effect because the resonating frequency is high.
- · Flipped geometry provides low inductance (less than 400 pH).
- · Provides stabilization of power line voltage.
- Suitable for IC decoupling application.

PC Board Pattern





Case	Dimensions (mm)				
Size	а	a b			
C0510	0.2	0.6	1.0		
C0816	0.3	1.0	1.6		
C1220	0.5	1.6	2.0		
C1632	0.75	2.2	3.2		

Applications



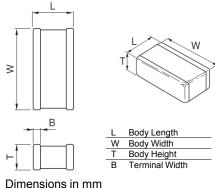
Shape &



- · Decoupling CPU power line
- · Bias line in CPU
- · High speed digital IC/decoupling
- · PC, cell phones, camcorders, etc.

Dimensions







Series Name

Dimensions L x W (mm)

Case Code	Length	Width
C0510	0.52 ± 0.05	1.00 ± 0.05
C0816 (C<1µF)	0.80 ± 0.10	1.60 ± 0.10
C0816 (C≥1µF)	0.80 ± 0.15	1.60 ± 0.20
C1220	1.25 ± 0.20	2.00 ± 0.20
C1608	1.60 ± 0.20	3.20 ± 0.20

Temperature Characteristic

Temperature Characteristics	Capacitance Change	Temperature Range
X5R	± 15%	-55 to +85°C
X6S	± 22%	-55 to +105°C
X7R	± 15%	-55 to +125°C
X7S	± 22%	-55 to +125°C

Rated Voltage (DC)

Voltage Code	Voltage (DC)
0G	4V
0J	6.3V
1A	10V
1C	16V
1E	25V
1H	50V

1632 X5R OJ 106 M T XXXX

Internal Codes Packaging Style

Packaging Code	Style	
T	Tape & Reel	
Capacitance Tole	rance	
Tolerance Code	Tolerance	
K	±15%	

Nominal Capacitance (pF)

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

Capacitance Code	Capacitance
0R5	0.5pF
010	1pF
102	1,000pF (1nF)
105	1,000,000pF (1µF)
	010 102





C0510 [EIA CC0204]

Capacitance Range Chart

Temperature Characteristics: X6S (± 22%)

Rated Voltage: 4V (0G)

Capacitance (pF)	Cap Code	Tolerance	X6S 0G (4V)
10,000	103	M: ± 20%	
22,000	223		
47,000	473		
100,000	104		
220,000	224		
470,000	474		
1,000,000	105		
2,200,000	225		

Standard Thickness



0.30 mm



C0510 [EIA CC0204]

Class 2 (Temperature Stable)

Temperature Characteristics X6S (-55 to +105°C, ±22%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0510X6S0G104M	X6S	4V	100,000	± 20%	0.30 ± 0.05
C0510X6S0G224M	X6S	4V	220,000	± 20%	0.30 ± 0.05
C0510X6S0G474M	X6S	4V	470,000	± 20%	0.30 ± 0.05





C0816 [EIA CC0306]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X7S (± 22%), X5R (± 15%), X6S (± 22%)

Rated Voltage: 16V (1C), 10V (1A), 6.3V (0J), 4V (0G)

Canacitanas	Con		X.	7R	X7S	X	5R	X6S	
Capacitance (pF)	Cap Code	Tolerance	1C (16V)	0J (6.3V)	0G (4V)	1A (10V)	0J (6.3V)	0G (4V)	
10,000	103	K: ± 10%							
22,000	223	M: ± 20%							
47,000	473								
100,000	104								
220,000	224								
470,000	474								
1,000,000	105								Sta
2,200,000	225								

Standard Thickness
0.50 mm



Capacitance Range Table

C0816 [EIA CC0306]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125°C, ±15%), X7S (-55 to +125°C, ±2%), X5R (-55 to +85°C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0816X7R1C103K	X7R	16V	10,000	± 10%	0.50 ± 0.10
C0816X7R1C223K	X7R	16V	22,000	± 10%	0.50 ± 0.10
C0816X7R1C473K	X7R	16V	47,000	± 10%	0.50 ± 0.10
C0816X7R1C104K	X7R	16V	100,000	± 10%	0.50 ± 0.10
C0816X7R0J224K	X7R	6.3V	220,000	± 10%	0.50 ± 0.10
C0816X7S0G474K	X7S	4V	470,000	± 10%	0.50 ± 0.10
C0816X7S0G105M	X7S	4V	1,000,000	± 20%	0.50 ± 0.10
C0816X7S0G225M	X7S	4V	2,200,000	± 20%	0.50 ± 0.10
C0816X5R1A224K	X5R	10V	220,000	± 10%	0.50 ± 0.10
C0816X5R1A474K	X5R	10V	470,000	± 10%	0.50 ± 0.10
C0816X5R0J474K	X5R	6.3V	470,000	± 10%	0.50 ± 0.10
C0816X5R0J105M	X5R	6.3V	1,000,000	± 20%	0.50 ± 0.10
C0816X5R0J225M	X5R	6.3V	2,200,000	± 20%	0.50 ± 0.10





C1220 [EIA CC0508]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X5R (± 15%) Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3V (0J)

Consoltones	Con			X7R			
Capacitance (pF)	Cap Code	Tolerance	1H (50V)	1E (25V)	1C (16V)	0J (6.3V)	1A (10V)
10,000	103	K: ± 10%					
22,000	223	M: ± 20%					
47,000	473						
100,000	104						
220,000	224						
470,000	474						
1,000,000	105						

Standard Thickness
0.85 mm



C1220 [EIA CC0508]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125 $^{\circ}$ C, ±15%), X5R (-55 to +85 $^{\circ}$ C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C1220X7R1H103K	X7R	50V	10,000	± 10%	0.85 ± 0.10
C1220X7R1H223K	X7R	50V	22,000	± 10%	0.85 ± 0.10
C1220X7R1H473K	X7R	50V	47,000	± 10%	0.85 ± 0.10
C1220X7R1E104K	X7R	25V	100,000	± 10%	0.85 ± 0.10
C1220X7R1C224K	X7R	16V	220,000	± 10%	0.85 ± 0.10
C1220X7R0J474K	X7R	6.3V	470,000	± 10%	0.85 ± 0.10
C1220X7R0J105M	X7R	6.3V	1,000,000	± 20%	0.85 ± 0.10
C1220X5R1A474K	X5R	10V	470,000	± 10%	0.85 ± 0.10
C1220X5R1A105M	X5R	10V	1,000,000	± 20%	0.85 ± 0.10



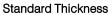


C1632 [EIA CC0612]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X7S (± 22%), X5R (± 15%) Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3 (0J), 4V (0G)

Consoitance	Con	X7R					X7S	X5R		
Capacitance (pF)	Cap Code		Tolerance	1H (50V)	1E (25V)	1C (16V)	0J (6.3V)	0G (4V)	1A (10V)	0J (6.3V)
10,000	103	K: ± 10%								
22,000	223	M: ± 20%								
47,000	473									
100,000	104									
220,000	224									
470,000	474									
1,000,000	105									
2,200,000	225									
4,700,000	475									
10,000,000	106									



0.70 mm

1.15 mm

1.30 mm



MULTILAYER CERAMIC CHIP CAPACITORS



C1632 [EIA CC0612]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125°C, ±15%), X7S (-55 to +125°C, ±2%), X5R (-55 to +85°C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C1632X7R1H103K	X7R	50V	10,000	± 10%	0.70 ± 0.10
C1632X7R1H223K	X7R	50V	22,000	± 10%	0.70 ± 0.10
C1632X7R1H473K	X7R	50V	47,000	± 10%	0.70 ± 0.10
C1632X7R1H104K	X7R	50V	100,000	± 10%	0.70 ± 0.10
C1632X7R1H224K	X7R	50V	220,000	± 10%	1.15 ± 0.10
C1632X7R1E224K	X7R	25V	220,000	± 10%	0.70 ± 0.10
C1632X7R1E474K	X7R	25V	470,000	± 10%	1.15 ± 0.10
C1632X7R1C474K	X7R	16V	470,000	± 10%	0.70 ± 0.10
C1632X7R1C105K	X7R	16V	1,000,000	± 10%	1.15 ± 0.10
C1632X7R0J105M	X7R	6.3V	1,000,000	± 20%	0.70 ± 0.10
C1632X7R0J225M	X7R	6.3V	2,200,000	± 20%	1.15 ± 0.10
C1632X7S0G475M	X7S	4V	4,700,000	± 20%	1.30 ± 0.10
C1632X7S0G106M	X7S	4V	10,000,000	± 20%	1.30 ± 0.10
C1632X5R1A105M	X5R	10V	1,000,000	± 20%	0.70 ± 0.10
C1632X5R1A225M	X5R	10V	2,200,000	± 20%	1.15 ± 0.10
C1632X5R0J475M	X5R	6.3V	4,700,000	± 20%	1.30 ± 0.10
C1632X5R0J106M	X5R	6.3V	10,000,000	± 20%	1.30 ± 0.10



Capacitors

No.	Item	Performance			Test or I	Test or Inspection Method				
1	External Appearance	No defects which may affect performance.			Inspect wi	Inspect with magnifying glass (3 $ imes$).				
2	Insulation Resistance	10,000M Ω or 500M Ω •μF min. (whichever smaller). As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, 100M Ω •μF min.			Apply rate	ed vo	oltage for 60s.			
3	Voltage Proof			st voltage w akdown or	ithout other damage.			ted voltage for narge current s	1 ~ 5s. shall not exceed 50mA.	
4	Capacitance	Within	Within the specified tolerance.			Measur Freque	_	Rated Voltage	Measuring Voltage	
						1kHz±1	0%	50V ~ 6.3V 4V	1.0±0.2 V _{rms} 0.5 - 5 V _{rms}	
5	Dissipation	T.C.	Rated	d Voltage	D.F.	See No.4	in th	is table for me	easuring condition.	
	Factor (Class 2)	X7R	R 16V, 10V, 6.3V R DC S S 4V DC		0.03 max.					
		X7R X5R			0.05 max.					
		X7S X6S X5S			0.12 max.					
6	Temperature Characteristics			Change (%)	•			red by the steps shown in mal equilibrium is obtained	
	of Capacitance	T.C		Δ C Perc	ent	for each s	step.			
	(Class 2)	X5	R	±15%		∆C be cal	culat	ted ref. STEP3	3 reading	
		X7		± 1370	<u> </u>			perature (°C)		
		X5 X6		±22%				rence temp. ± 2		
		X7:		- 22 /0				operating temp. \pm 2		
								operating temp		
7	Robustness of Terminations		No sign of termination coming off, breakage of ceramic, or other abnormal signs.				1) aı	nd apply a pus	on P.C. board (shown in shing force of 5N (C0510: - 5N (2N for C0510) P.C.Board	



No.	Item	Performance		Test or Inspection Method		
8	Bending	No mechanical da	mage.	Reflow solder the capacitor on P.C. board (shown in Appendix 2) and bend it for 1mm.		
				50 F R230 Unit: mm		
9	Solderability	New solder to cover termination.	er over 75% of	Completely soak both terminations in solder at 235 \pm 5°C for 2 \pm 0.5s.		
		25% may have pin but not concentrate	holes or rough spots ed in one spot.	Solder: H63A (JIS Z 3282) Flux: Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.		
		Ceramic surface or not be exposed du shifting of terminat	e to melting or			
			A section			
10	Resistance to so	older heat		Completely soak both terminations in solder at 260 \pm 5°C for 5 \pm 1s.		
	External		wed and terminations			
	appearance	shall be covered a solder.	t least 60% with new	Preheating condition Temp.: 150 ± 10°C		
	Capacitance	Characteristics	Change from the value before test	Time: 1 ~ 2min.		
		Class 2 X7R X7S X5R X6S	± 7.5 %	Flux: Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.		
	D.E. (Class 2)		1	Solder: H63A (JIS Z 3282)		
	D.F. (Class 2)	Meet the initial spe		Leave the capacitor in ambient conditions for 24 \pm 2h before measurement.		
	Insulation Resistance	Meet the initial spe	ec.	_		
	Voltage proof	No insulation brea	kdown or other			

damage.



No.	Item	Performa	Performance			Inspection Method				
11	Vibration External	No mecha	nical daı	mage.	Solder the capacitors on P.C. board (shown in Appendix 1) before testing.					
	appearance Capacitance	Ch. Chi		Change from the	Vibrate the capacitor with amplitude of 1.5mm P-P changing the frequencies from 10Hz to 55Hz and bac to 10Hz in about 1min.					
	Oapaolarice	Characteri	stics	value before test						
		Class 2	X7R X7S X5R X6S	± 7.5 %	Repeat this for 2h each in 3 perpendicular direct					
	D.F. (Class 2)	Meet the ir	nitial spe	ec.	_					
12	Temperature cycle)				ne capacitors on P.C. boar	d (shown in			
	External appearance	No mecha	No mechanical damage.			Appendix 1) before testing. Expose the capacitor in the conditions step1 through and repeat 5 times consecutively.				
	Capacitance			Change from the value before test	Leave th	ne capacitor in ambient con	ditions for 24 \pm 2h			
			X7R			neasurement.				
		Class 2	X7S X5R	± 7.5 %	Step	Temperature (°C)	Time (min.)			
		X				Min. operating temp. ±3	30 ± 3			
			703		_ 2	Reference Temp.	2 – 5			
-	D.F. (Class 2)	Meet the initial spec.			3	Max. operating temp. \pm 2	30 ± 2			
	Insulation Resistance	1,000MΩ o smaller.	or 50MΩ	•μF min. whichever	<u> 4</u>	Reference Temp.	2 - 5			
	Voltage Proof	No insulati damage.	on brea	kdown or other	_					
13	Moisture Resistan	ce (Steady	State)			ne capacitor on P.C. board	I (shown in			
	External appearance	No mecha	nical daı	mage.	Appendix 1) before testing. Leave at temperature 40 \pm 2°C, 90 to 95%RH for 500 \pm +24.0h					
	Capacitance	Characteri	stics	Change from the value before test	Leave th	$_{\pm}~$ +24, 0h. Leave the capacitor in ambient conditions for 24 \pm 2h				
		Class 2	X7R X7S X5R X6S	± 12.5 %	before n	neasurement.				
	D.F. (Class 2)	X7S: 200° X5R: 200°	% of initi % of initi % of initi	al spec. max. al spec. max. al spec. max. al spec. max.						
	Insulation Resistance	1,000MΩ or 50MΩ•μF min. (whichever smaller). As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, $10MΩ•μF$ min.								

MULTILAYER CERAMIC CHIP CAPACITORS

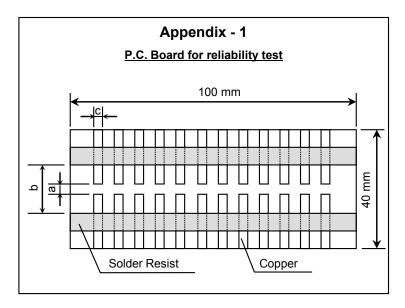


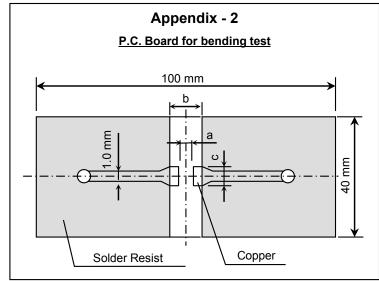
C Series – Low ESL Flip Type

No.	Item	Performa	nce		Test or Inspection Method		
14	Moisture Resista External appearance	Ğ			Solder the capacitors on P.C. board (shown in Appendix 1) before testing. Apply the rated voltage at temperature 40 \pm 2°C and		
	Capacitance	Characteristics Change from the value before test			90 to 95%RH for 500 +24, 0h.Charge/discharge current shall not exceed 50mA.		
		Class 2	X7R X7S X5R X6S	± 12.5 %	Leave the capacitor in ambient conditions for 48 ± 4h before measurement. Voltage conditioning:		
	D.F. (Class 2)	X7S: 200% X5R: 200%	of initia of initia of initia	al spec. max. al spec. max. al spec. max. al spec. max.	 Voltage treats the capacitor under testing temperature and voltage for 1hour. Leave the capacitor in ambient conditions for 24 ± 2h before measurement. Use this measurement for initial value. 		
	Insulation Resistance	smaller). A	s for th	uF min. (whichever e capacitor of rated a and 4V DC, 5MΩ•μF			
15	Life External appearance	No mechar	nical dai	mage.	Reflow Solder the capacitor on P.C. board (shown in Appendix 1) before testing. Apply rated voltage at maximum operating temperature		
	Capacitance	Characteris	1	Change from the value before test	± 2°C for 1,000 +48, 0h.Charge/discharge current shall not exceed 50mA.		
		Class 2	Class 2		Leave the capacitor in ambient conditions for 24 ± 2h before measurement. Voltage conditioning:		
	D.F. (Class 2)	X7S: 200% X5R: 200%	of initia of initia of initia	al spec. max. al spec. max. al spec. max. al spec. max.	 Voltage treats the capacitor under testing temperature and voltage for 1hour. Leave the capacitor in ambient conditions for 48 ± 4h before measurement. Use this measurement for initial value. 		
	Insulation Resistance	1,000MΩ or 50MΩ•μF min. whichever smaller. As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, 10MΩ•μF min.					

^{*}As for the initial measurement of capacitors on number 6, 10, 11, 12 and 13, leave capacitor at 150 -10, 0° C for 1h and measure the value after leaving capacitor for 24 \pm 2h in ambient condition.







Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: Appendix 1,2

1.6mm

Copper (thickness 0.035mm)

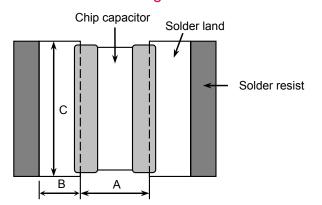
Solder resist

Case	Code	Dimensions (mm)				
JIS	JIS EIA		b	С		
C0510	CC0204	0.2	0.6	1.0		
C0816	CC0306	0.3	1.0	1.6		
C1220	CC0508	0.5	1.6	2.0		
C1632	C1632 CC0612		2.2	3.2		





Recommended Soldering Land Pattern

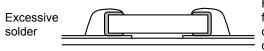


Reflow Soldering

Unit: mm

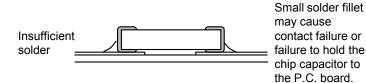
Type Symbol	C0510 [CC0204]	C0816 [CC0306]	C1220 [CC0508]	C1632 [CC0612]
A	0.20	0.30	0.50	0.75
В	0.20	0.35	0.55	0.725
С	1.00	1.60	2.00	3.20

Recommended Solder Amount

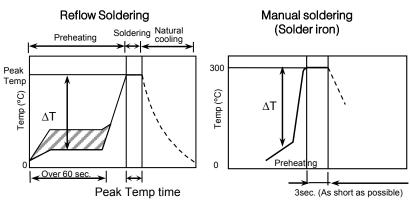


Higher tensile force on the chip capacitor may cause cracking.





• Recommended Soldering Profile



Recommended soldering duration

Temp./	Reflow S	oldering
Dura. Solder	Peak temp (°C)	Duration (sec.)
Sn-Pb Solder	230 max.	20 max.
Lead-Free Solder	260 max.	10 max.

Recommended solder compositions

Sn-37Pb (Sn-Pb solder)

Sn-3.0Ag-0.5Cu (Lead Free Solder)

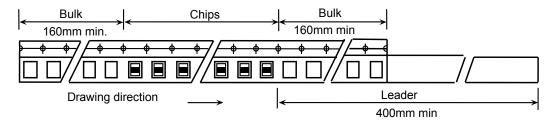
Preheating Condition

Soldering	Temp. (°C)
Reflow soldering	ΔT ≤ 150
Manual soldering	ΔT ≤ 150

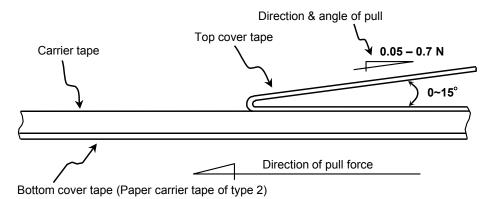




Carrier Tape Configuration

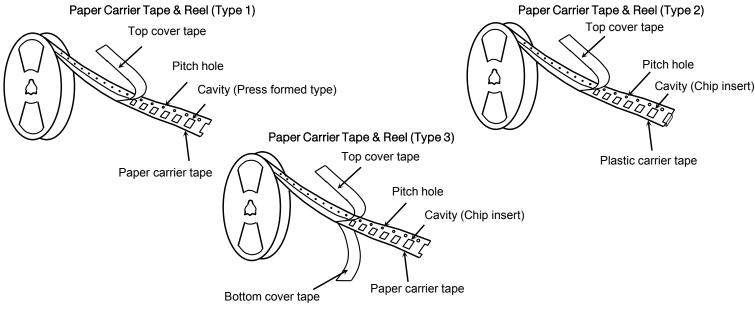


Peel Back Force (Top Tape)



- Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.
- The missing of components shall be less than 0.1%
- · Components shall not stick to the cover tape.
- The cover tape shall not protrude beyond the edges of the carrier tape not shall cover the sprocket holes.

Chip Quantity Per Reel and Structure of Reel (Paper & Plastic)

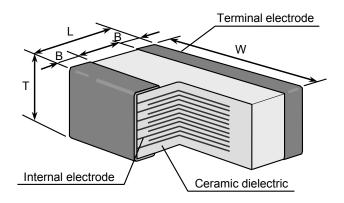


Case Code		Chip	Taning Material	Chip quantity (pcs.)		
JIS	EIA	Thickness	Taping Material	φ178mm (7") reel	φ330mm (13") reel	
C0510	CC0204	0.50 mm	Paper (Type 1)	15,000	50,000	
C0816	CC0306	0.80 mm	Plastic (Type 3)	4,000	10,000	
C1220	CC0508	0.85 mm	Paper (Type 2)	4,000	10,000	
		0.70 mm		4,000		
C1632	CC0612	1.15 mm	Plastic (Type 3)	2,000	10,000	
		1.30 mm		2,000		



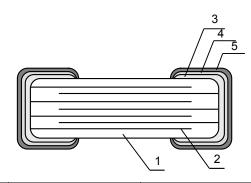


Shape & Dimensions



Case	Code	Dimensions (mm)					
JIS	EIA	L	W	Т	В	G	
C0510	CC0204	0.52	1.00	0.50	0.10 min.	0.09 min.	
C0816	CC0306	0.80	1.60	0.80	0.10 min.	-	
C1220	CC0508	1.25	2.00	0.85	0.20 min.	0.40 min.	
				0.70			
C1632	CC0612	1.60	3.20	1.15	0.20 min.	0.50 min.	
				1.30			

Inside Structure & Material System



No.	NAME	MATERIAL
		Class 2
(1)	Ceramic Dielectric	BaTiO ₃
(2)	Internal Electrode	Nickel (Ni)
(3)		Copper (Cu)
(4)	Termination	Nickel (Ni)
(5)		Tin (Sn)

C Series – Low ESL Flip Type

Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

- 1. Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- For REACH (SVHC: 15 substances according to ECHA / October 2008): All TDK MLCC do not contain these 15 substances.
- For European Directive 2000/53/CE and 2005/673/CE:
 Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.
- For European Directive 2003/11/CE: Pentabromodiphenylether, Octabromodiphenylether are not contained in all TDK MLCC.